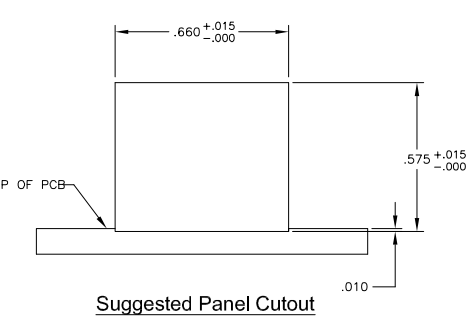
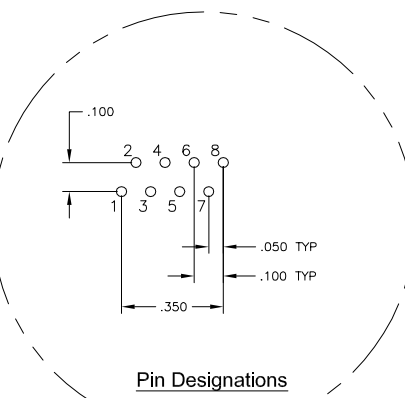
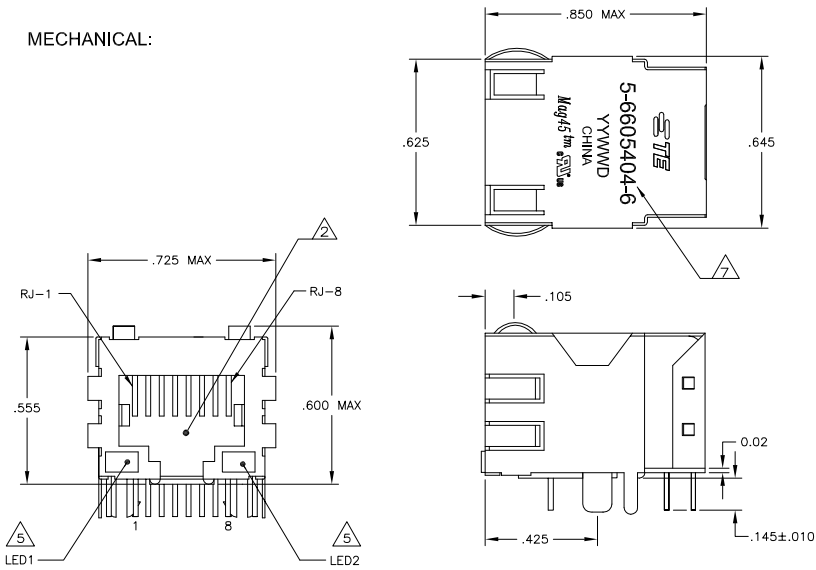


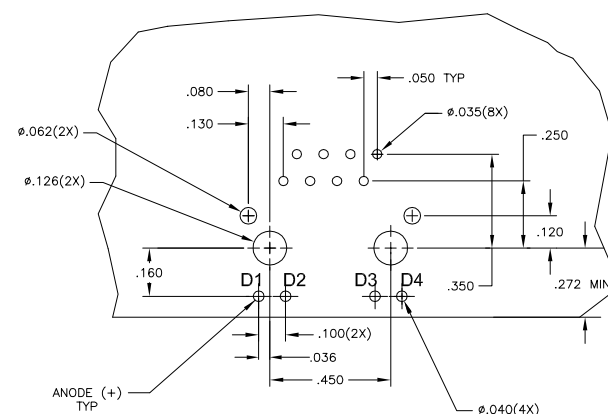
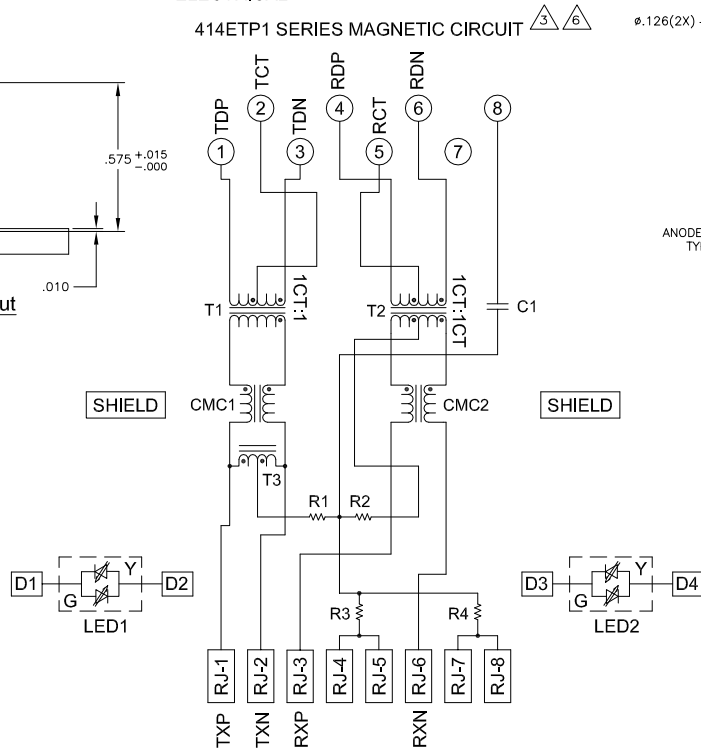
LOC	REV	DESCRIPTION	DATE	BY	APP
AA	22				
B		ECO-08-022357	01DEC2008	QL	TX
C		ECO-11-015766	30MAY2011	EL	LR

MECHANICAL:



ELECTRICAL:

414ETP1 SERIES MAGNETIC CIRCUIT



- MATERIALS:**
- HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0
 - SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30μINCH SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER.
 - MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE
 - SOLDERTAILS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP
 - LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
- RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.**
- MAGNETICS**
- IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP: CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM -40°C TO +85°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 4.0MHz
 - 33-20*LOG(f/50)dB MIN FROM 4.01MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
- 4. OPERATING TEMPERATURE: FROM -40°C TO +85°C INDUSTRIAL TEMPERATURE RATED.**
- LEDs ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20 mA**
- LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20 mA
 DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20 mA
 FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20 mA
- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE ASYMMETRIC, AND THEREFORE DO NOT SUPPORT AUTO-MDI/MDIX.**
- TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.**
- 8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.**

C1 = 1000 pF, 2kV DECOUPLING CAPACITOR
 R1-R4 = 75 OHMS, 1/16 W, 5% RESISTORS

GREEN/YELLOW		GREEN/YELLOW		5-6605404-6	
LED1		LED2		PART NUMBER	
<p>THIS DRAWING IS A CONTROLLED DOCUMENT. DATE: 07MAR2009 DWG: ATTADIA - 0022357 CHK: FAROLE 07MAR2009 APD: FAROLE 07MAR2009</p>					
DIMENSIONS: INCHES		NAME: 1X1 MAG45(TM), MODULAR JACK, 4N2ETP1 INDUSTRIAL TEMP SCHEMATIC, 414ETP1 MAGNETIC CIRCUIT, SHIELDED, WITH BICOLOR LEADS		PRODUCT SPEC: 108-2100	
MATERIAL: 1		FINISH: 2		WEIGHT: -	
CUSTOMER DRAWING		SCALE: NTS		SHEET 1 OF 1 REV C	

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)